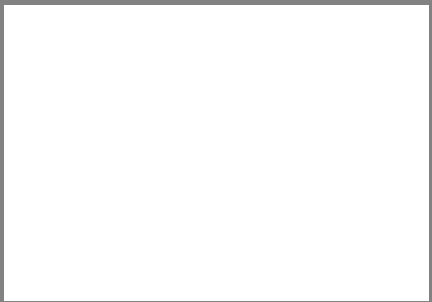




SEMICELL CAL-DIODE

SKCD

$I_F = A$
 $V_{RRM} = V$
Size: mm X mm
Package:

Features

Typical Applications



Absolute Maximum Ratings			
Symbol	Conditions	Values	Units
V_{RRM}	$T_{vj} = ^\circ C, I_R = mA$ $, T_{vjmax} = ^\circ C$ $T_{vj} = ^\circ C,$ $T_{vjmax} = ^\circ C,$		V
$I_{F(AV)}$			A
I_{FSM}			A
			A
T_{vjmax}			$^\circ C$

Electrical Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
I^2t	T_{vjmax}				A ² s
I_R	$T_{vj} = ^\circ C, V_{RRM}$ $T_{vj} = ^\circ C, V_{RRM}$ $T_{vj} = ^\circ C, I_F = A$ $T_{vj} = ^\circ C, I_F = A$				mA
					mA
V_F					V
					V
$V_{(TO)}$	$T_{vj} = ^\circ C$				V
r_T	$T_{vj} = ^\circ C$				m Ω

Dynamic Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
t_{rr}	$T_{vj} = ^\circ C, V, A/\mu s$				ns
	$T_{vj} = ^\circ C, V, A/\mu s$				ns
Q_{rr}	$T_{vj} = ^\circ C, A, V, A/\mu s$				μC
	$T_{vj} = ^\circ C, A, V, A/\mu s$				μC
I_{rrm}	$T_{vj} = ^\circ C, A, V, A/\mu s$				A
	$T_{vj} = ^\circ C, A, V, A/\mu s$				A

Thermal Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
T_{vj}					$^\circ C$
T_{stg}					$^\circ C$
T_{solder}	min				$^\circ C$
T_{solder}	min				$^\circ C$
					K / W

Mechanical Characteristics		
Parameter		Units
raster size		mm
Area total		mm ²
Chips / wafer		pcs
Anode metallisation		
Cathode metallisation		
wire bond		

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